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HSB320 thru HSB3100

Schottky Barrier Rectifiers (Reverse Voltage 20 to 100V, Forward Current 3A)

Features

- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability

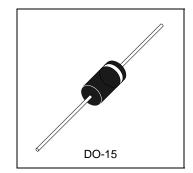
Mechanical Data

- Cases: DO-15 molded plastic body
- Epoxy: UL 94V-0 rate flame retardant
- Lead: Axial leads, solderable per MIL-STD-202, Method 208 guaranteed
- Polarity: Color band denotes cathode end
- High temperature soldering guaranteed: 250°C/10seconds/.375"(9.5mm) lead lengths at 5lbs.(2.3kg) tension
- Weight: 0.4gram

Maximum Ratings & Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load. Derate current by 20%.

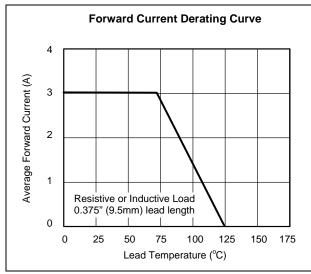
Ratings	Symbol	HSR 320	HSR 330	HSR 340	HSR 350	HSR 360	HSR 380	HSR 3100	Unit
Repetitive Peak Reverse Voltage	V_{RRM}	20	30	40	50	60	80	100	V
Surge Peak Reverse Voltage	V _{RSM}	14	21	28	35	42	57	71	V
DC Blocking Voltage	V_{DC}	20	30	40	50	60	80	100	V
Average Forward Rectified Current (T _A =75°C)	I _{FAV}	3							Α
Peak Forward Surge Current, 50Hz Half Sine-wave (T _A =25°C)	I _{FSM}	80							А
Repetitive Peak Forward C (f>15Hz)	I _{FRM}	12							Α
Instantaneous Forward Voltage	V _F	0.48	0.52 0.7			0.8		V	
Leakage Current (T _J =25°C, V _R =V _{RRM})	0.1								mA
Leakage Current (T _J =100°C, V _R =V _{RRM})	IR	10							mA
Typical Junction Capacitance	CJ	170							pF
Rating for Fusing, t<10ms (T _A =25°C)	i ² t	12.5							A ² s
Thermal Resistance Junction to Ambient Air	$R_{\theta JA}$	50							°C/W
Thermal Resistance Junction to Lead	$R_{\theta JL}$	15							°C/W
Operating Junction Temperature Range	TJ	-65 to +125							°C
Storage Temperature Range	T _{STG}	-65 to +150							°C
ESD Protection Voltage	V _{ESD}	<8							KV

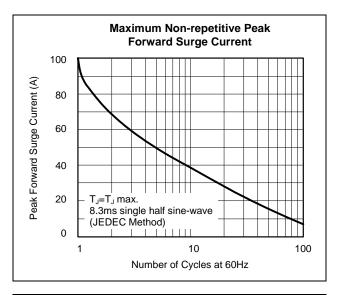


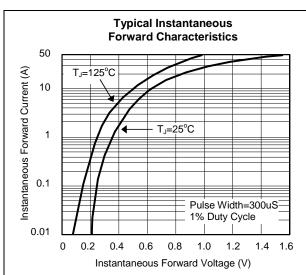
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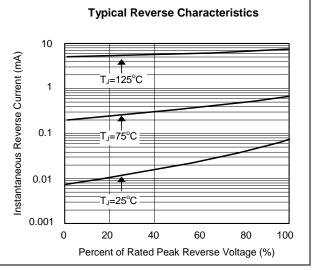
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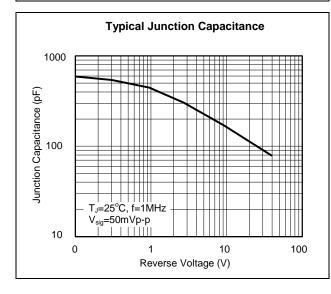
Characteristics Curve

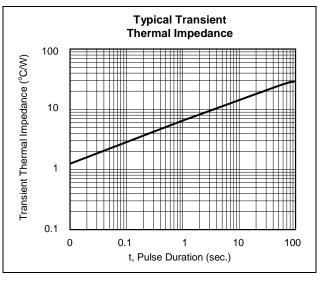








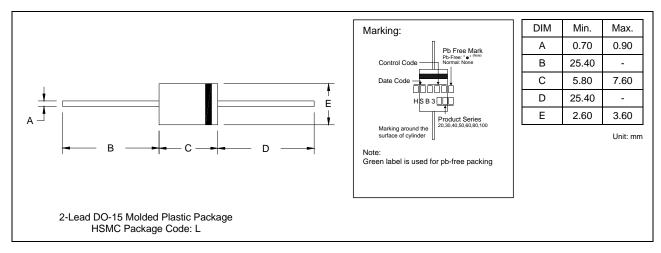




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DO-15 Dimension



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